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# In-Mold Assembly: A New Approach to Assembly Automation

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Sponsors: NSF and ARO MURI



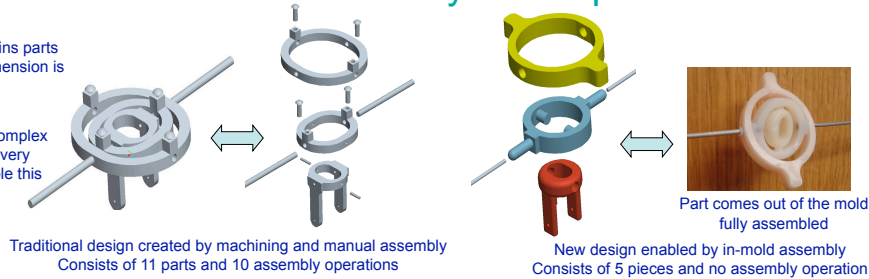
## In-Mold Assembly Concept

### Goals

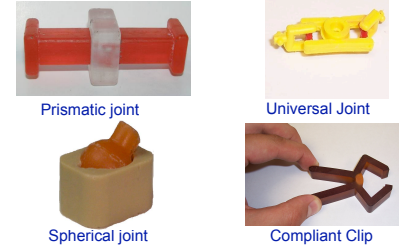
- Develop mold design templates to develop mesoscale joints
- Develop model to estimate deformation of premolded components and alternate ways to control it
- Develop an understanding of in-mold assembly clearances
- Develop design templates to embed electronics and actuators in mold
- Develop models to understand heat dissipation of actuators embedded in polymers

This design contains parts whose largest dimension is less than 2 mm

Small parts and complex geometry make it very difficult to assemble this MAV swashplate

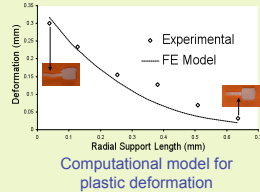
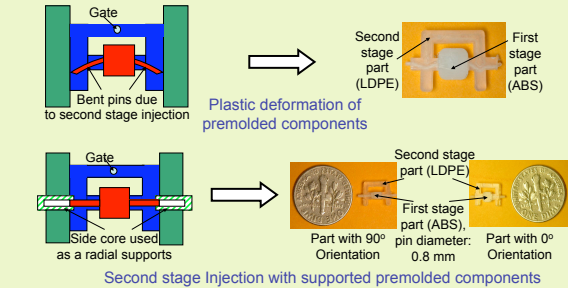


### Capabilities



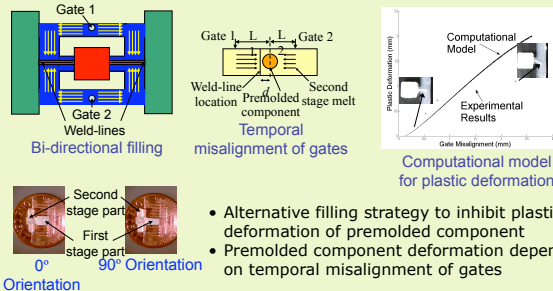
## Process Characterization and Modeling

### Unidirectional Filling for In-Mold Assembly of Mesoscale Revolute Joints



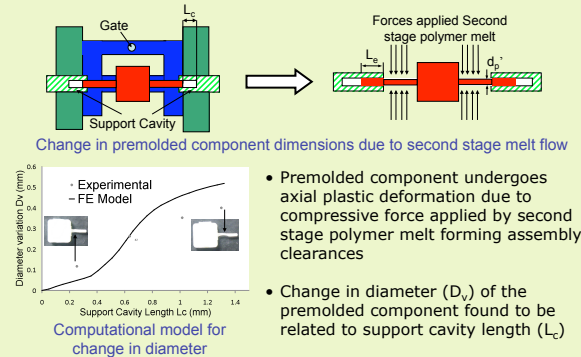
- We were the first research group to successfully realize mesoscale revolute joint using in-mold assembly
- 25% radial support found to be optimum for mold geometry and ABS/LDPE combination

### Bi-directional Filling for In-Mold Assembly of Mesoscale Revolute Joints



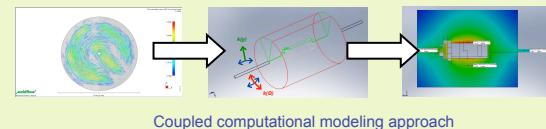
- Alternative filling strategy to inhibit plastic deformation of premolded component
- Premolded component deformation dependent on temporal misalignment of gates

### Joint Clearances during In-Mold Assembly of Mesoscale Revolute Joints



### Embedding Actuators

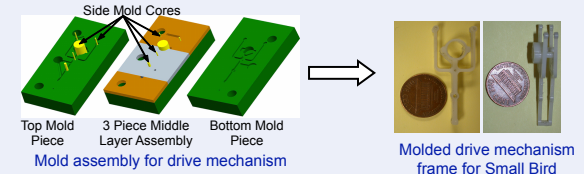
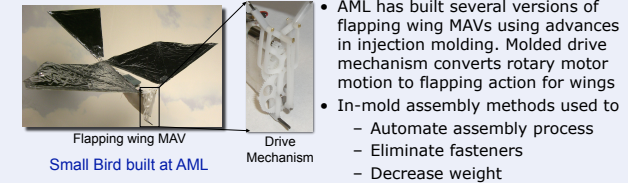
- We use thermally conductive polymer composites to create multi functional structures with embedded actuators
  - Anchoring of the embedded actuator
  - Dissipation of heat produced by the actuator
- Coupled modeling approach:
  - Polymer melt flow inside the mold to obtain fiber orientations
  - Orthotropic thermal conductivity models from molding process to assess heat dissipation



- Research results:
  - 40% reduction in the operating temperature of the embedded actuator
  - Polymers with  $k > 2$  W/m-K do not require orthotropic thermal conductivity modeling

## Applications

### Flapping Wing MAV



	Small Bird	Big Bird	Big Bird with vision	Big Bird with folding wings
Overall Weight	12.8 g	35.0 g	42.2 g	36.9 g
Wing Span	34.3 cm	57.2 cm	57.2 cm	57.2 cm
Flapping frequency	12.1 Hz	4.5 Hz	4.5 Hz	4.5 Hz
Payload Capacity	2.5 g	12.0 g	4.8 g	10.0 g

Attributes of different MAVs built at AML

### Miniature Robot

